

Dual Precision JFET-Input Operational Amplifier

OP-215

FEATURES

•	High Slew Rate 10V/μs Min
	Fast Settling Time 0.9 µs to 0.1% Typ
	Low Input Offset Voltage Drift 10μV/°C Max
•	Wide Bandwidth 3.5MHz Min
•	Temperature-Companyated Input Bigs Currents

- Guaranteed Input Bias Current 18nA Max (125°C)
- Bias Current Specified Warmed-Up Over Temperature
- Low Input Noise Current 0.01pA/\(\sqrt{Hz}\) Typ
- High Common-Mode Rejection Ratio 86dB Min
- Pin Compatible With Standard Dual Pinouts
- 125° C Temperature Tested DICE
- Models With MIL-STD-883 Class B Processing Available
- Available in Die Form

ORDERING INFORMATION 1

T_= 25°C	:	PACKAGE									
V _{oe} MAX (mV)	TO-99	CERDIP 8-PIN	PLASTIC 8-PIN	LCC 20-CONTACT	TEMPERATURE RANGE						
1.0 C	P215AJ*	OP215AZ*	_	_	MIL						
1.0 C	P215EJ	OP215EZ	OP215EP	_	СОМ						
2.0 C	P215BJ/883	OP215BZ/883	- (DP215BRC/88	3 MIL						
2.0 C	P215FJ	OP215FZ	OP215FP	_	COM						
4.0 C	P215CJ/883	OP215CZ/883	-	_	MIL						
6.0	-	OP215GZ	OP215GP	_	XIND						
6.0	_	_	OP215GS	_	XIND						

- For devices processed in total compliance to MIL-STD-883, add /883 after part number. Consult factory for 883 data sheet.
- Burn-in is available on commercial and industrial temperature range parts in CerDIP, plastic DIP, and TO-can packages.

GENERAL DESCRIPTION

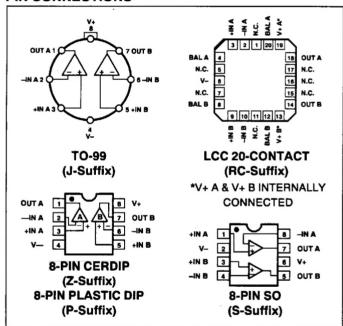
The OP-215 offers the proven JFET-input performance advantages of high speed and low input bias current with the tracking and convenience advantages of a dual op-amp configuration.

Low input offset voltages, low input currents, and low drift are featured in these high-speed amplifiers.

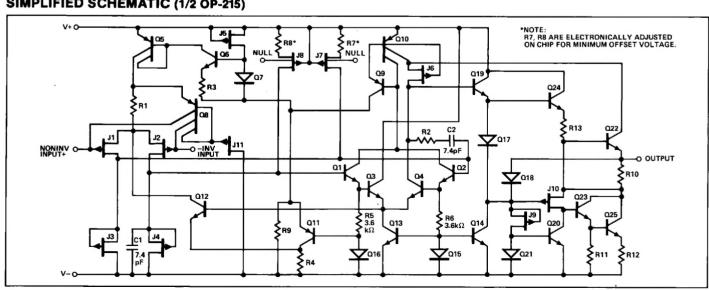
On-chip zener-zap trimming is used to achieve low VOS while a bias-current compensation scheme gives a low input bias current at elevated temperatures. Thus the OP-215 features an input bias current of 18nA at 125°C ambient (not junction) temperature which greatly extends the application usefulness of this device.

Applications include high-speed amplifiers for current output DACs, active filters, sample-and-hold buffers, and photocell

PIN CONNECTIONS



SIMPLIFIED SCHEMATIC (1/2 OP-215)



OP-215

GENERAL DESCRIPTION Continued

amplifiers. For additional precision JFET op amps, see the OP-15/16/17 data sheet.

ABSOLUTE MAXIMUM RATINGS (Note 1)

ABOOLOTE INFAMION TO COMPANY
Supply Voltage
OP-215A, OP-215B, OP-215E, OP-215F
(All DICE Except GR)±22V
OP-215C, OP-215G (GR DICE Only)±18V
Operating Temperature Range
OP-215A, OP-215B, OP-215C55°C to +125°C
OP-215E, OP215F0°C to + 70°C
OP-215G40°C to +85°C
Maximum Junction Temperature (T _i) +150°C
Differential Input Voltage
OP-215A, OP-215B, (All DICE Except GR) ±40V
OP-215E, OP-215F, (All DICE Except GR) ±40V
OP-215C, OP-215G, (GR DICE Only) ±30V
Input Voltage
OP-215A, OP-215B, (All DICE Except GR) ±20V
OP-215E, OP-215F, (All DICE Except GR) ±20V

OP-215C, OP-215G,	(GR DICE Only)		±16V
(Unless otherwise sp			
tive input voltage is e	gual to one volt mo	re positive	than the
negative power supp		•	
Output Short-Circuit Du			Indefinite
Storage Temperature F			
Lead Temperature (So			
Junction Temperature			
PACKAGE TYPE	Θ _{jA} (NOTE 2)	ejc	UNITS
TO-99 (J)	145	16	°C/W
8-Pin Hermetic DIP (Z)	134	12	°C/W
8-Pin Plastic DIP (P)	96	37	°C/W
20-Contact LCC (RC)	88	33	°C/W

NOTES

8-Pin SO (S)

Absolute maximum ratings apply to both DICE and packaged parts, unless otherwise noted.

150

41

°C/W

N_{jA} is specified for worst case mounting conditions, i.e., O_{jA} is specified for device in socket for TO, CerDIP, P-DIP, and LCC packages; O_{jA} is specified for device soldered to printed circuit board for SO package.

ELECTRICAL CHARACTERISTICS at $V_S = \pm\,15V$, $T_A = 25^{\circ}\,C$, unless otherwise noted.

			0	P-215A	/E	O	P-215B	/F	O	P-215C	/G	
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Input Offset Voltage	v _{os}	R _S = 50Ω	_	0.2	1.0	_	0.8	2.0	_	2.0 2.5	4.0 6.0	mV
Input Offset Current	los	'G' Grade T _j = 25°C (Note 1)		3 5	50 100		3 5	50 100		3 5	100	pA
Input Bias Current		Device Operating T _j = 25° C (Note 1)		± 15	±100		±15	±200	_	±15	±300	pA
Input Bias Current	IB	Device Operating		± 18	±300		±18	±400	-	±18	±600	
Input Resistance	R _{IN}			1012			1012			10.2		- 11
Large-Signal Voltage Gain	Avo	$R_L \ge 2k\Omega$ $V_O = \pm 10V$	150	500		75	220		50	200	_	V/mV
Output Voltage Swing	v _o	$R_L = 10k\Omega$ $R_L = 2k\Omega$	±12 ±11	±13 ±12.7	_	±12 ±11	±13 ±12.7	_	±12 ±11	±13 ±12.7	_	v
Supply Current	İsy	'G' Grade		6.0	8.5	_	6.0	8.5	_	7.0 7.0	10.0 12.0	mA
Slew Rate	SR	A _{VCL} =+1	10	18	_	7.5	18	_	5	15		V/μs
Gain Bandwidth Product	GBW	(Note 3)	3.5	5.7	_	3.5	5.7	_	3.0	5.4		MHz
Closed-Loop Bandwidth	CLBW	A _{VCL} = +1	_	13	-	_	13	_	_	12	_	MHz
Settling Time	ts	to 0.01% to 0.05% (Note 2)	-	2.3 1.1 0.9	_ _	_	2.3 1.1 0.9	_ _	-	2.4 1.2 1.0	_	μ8
Input Voltage Range	IVR	to 0.10%	+10.2	+14.8		+10.2 -10.2	+14.8	_	+10.1 -10.1	+14.8	_	٧
Common-Mode Rejection Ratio	CMRR	V _{CM} = ±IVR A, B, C Grades E, F, G Grades	-10.2 86 82	-11.5 100 100	-	86 82	100	=	82 80	96 96	_	dB
Power Supply Rejection Ratio	PSRR	$V_S = \pm 10V \text{ to } \pm 16V$ $V_S = \pm 10V \text{ to } \pm 15V$	=	10	51 —	=	10	80	_	_ 16	100	μV/V
Input Noise Voltage Density	en	f _O = 100Hz f _O = 1000Hz	=	20 15	=	_	20 15	_	_	20 15		nV/√Hz
Input Noise Current Density	in	f _O = 100Hz f _O = 1000Hz	=	0.01 0.01	_	_	0.01 0.01	_	_	0.01 0.01		p A /√Hz
Input Capacitance	C _{IN}		_	3	_	_	3	_	_	3	_	pF

ELECTRICAL CHARACTERISTICS at $V_S = \pm 15V$, -55° C $\leq T_A \leq +125^{\circ}$ C, unless otherwise noted.

		;	OP-215A			OP-215B			OP-215C			
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Input Offset Voltage	Vos	$R_S = 50\Omega$	-	0.5	2.0	_	1.5	3.0		3.0	6.0	mV
Average Input Offset Voltage Drift												
Without External Trim	TCVOS	(Note 3)	_	3	10	_	3	10	_	6	_	
With External Trim	TCVOSn	$R_p = 100k\Omega$	_	3	_	_	3	_	_	4	_	μV/°C
Input Offset Current		T _i = +125°C	_	0.8	8	_	0.8	8	_	1.0	12	
(Note 1)	los	T _A = +125°C, Device Operation	ng —	1.2	14	_	1.2	14	_	1.5	22	пА
Input Bias Current		T _i = +125°C	_	± 1.5	±10	_	±1.5	±10	_	±1.8	±15	
(Note 1)	I _B	TA = +125°C, Device Operation	ng —	±2.2	±18		±2.2	±18		±2.7	±28	nA
toput Voltage Banca	IVR		+10.2	+14.6	_	+10.2	+14.6	_	+10.1	+14.6	_	V
Input Voltage Range	IVN		-10.2	-11.3		-10.2	-11.3	_	-10.1	-11.3		v
Common-Mode Rejection Ratio	CMRR	V _{CM} = ±IVR	82	97	-	82	97	-	80	93	_	dB
Power Supply		$V_S = \pm 10V \text{ to } \pm 16V$	_	10	100	. –	15	100	_	_	_	1407
Rejection Ratio	PSRR	$V_S = \pm 10V \text{ to } \pm 15V$	_	_		_	_		_	23	126	μV/V
Large-Signal Voltage Gain	Avo	$R_L \ge 2k\Omega$ $V_O = \pm 10V$	30	110	_	30	110	_	25	100	_	V/mV
Output Voltage Swing	v _o	R _L ≥ 10kΩ	±12	±13	_	±12	±13	_	±12	±13	-	v

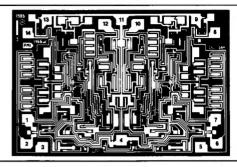
ELECTRICAL CHARACTERISTICS at $V_S = \pm 15V$, 0°C $\leq T_A \leq +70$ °C for E/F Grades, -40°C $\leq T_A \leq +85$ °C for G Grade, unless otherwise noted.

			OP-215E		(OP-215F			OP-215G			
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Input Offset Voitage	vos	$R_S = 50\Omega$	_	0.4	1.65	_	1.4	2.65		3.5	8.0	mV
Average Input Offset Voltage Drift												
Without External Trim	TCVOS	(Note 3)	_	3	15	_	3	15	_	6	_	140.0
With External Trim	TCVOSn	$R_P = 100k\Omega$	-	3	_	_	3	_	_	4	-	μV/°C
Input Offset Current		T _i = +70°C	_	0.06	0.45	_	0.06	0.45	_	0.08	0.65	- •
(Note 1)	los	T _A = +70°C, Device Operating	_	0.08	0.80	_	0.08	0.80	_	0.10	1.2	nA
Input Bias Current	I _B	T _i = +70°C	_	±0.12	±0.70	_	±0.12	±0.70	_	±0.14	±0.9	
(Note 1)		T _A = +70°C, Device Operating	_	±0.16	±1.40	_	±0.16	±1.40		±0.19	±1.8	nA
Inc. 4 Matters Bases	11.40		+10.2	+14.7	_	+10.2	+14.7	_	+10.1	+14.7	_	
Input Voltage Range	e IVR		-10.2	-11.4	_	-10.2	-11.4	_	-10.1	~11.3	_	_ v
Common-Mode Rejection Ratio	CMRR	V _{CM} = ± IVR	80	98	_	80	98	_	76	94	_	₫B
Power Supply	2022	V _S = ±10V to ±16V	_	13	100	_	13	100	-	_	_	
Rejection Ratio	PSRR	$V_8 = \pm 10 \text{V to } \pm 15 \text{V}$	_			_	_	_	_	20	159	μV/V
Large-Signal Voltage Gain	Avo	$R_L \ge 2k\Omega$ $V_O = \pm 10V$	50	180	-	50	180	-	35	130	-	V/mV
Output Voltage Swing	v _o	R _L ≥10kΩ	±12	±13	-	±12	±13	_	±12	±13	-	V

NOTES:

- Input bias current is specified for two different conditions. The T_j = 25° C specification is with the junction at ambient temperature; the Device Operating specification is with the device operating in a warmed-up condition at 25° C ambient. The warmed-up bias current value is correlated to the junction temperature value via the curves of I_Bvs. T_j and I_Bvs. T_A. PMI has a bias current compensation circuit which gives improved bias current and bias current over temperature vs. standard JFET input op amps. I_B and I_{OS} are measured at V_{CM} = 0.
- 2. Settling time is defined here for a unity gain inverter connection using $2k\Omega$ resistors. It is the time required for the error voltage (the voltage at the inverting input pin on the amplifier) to settle to within a specified percent of its final value from the time a 10V step input is applied to the inverter. See settling time test circuit.
- 3. Sample tested.

DICE CHARACTERISTICS (125°C TESTED DICE AVAILABLE)



1. INVERTING INPUT (A) 8. NULL (B) 9. V+

2. NONINVERTING INPUT (A)

3. NULL (A)

5. NULL (B)

6. NONINVERTING INPUT (B)

7. INVERTING INPUT (B)

12. V_O (A) 13. V+

10. V_O (B) 11. V+

14. NULL (A)

ALL V+ PADS ARE INTERNALLY CONNECTED.

DIE SIZE 0.110×0.075 inch, 8250 sq. mils

(2.79 imes 1.91 mm, 5.33 sq. mm)

WAFER TEST LIMITS at $V_S = \pm 15V$, $T_A = 25^{\circ}$ C for OP-215N, OP-215G and OP-215GR devices; $T_A = 125^{\circ}$ C for OP-215NT and OP-215GT devices, unless otherwise noted.

PARAMETER	SYMBOL	CONDITIONS	OP-215NT LIMIT	OP-215N LIMIT	OP-215GT	OP-215G LIMIT	OP-215GR LIMIT	UNITS
Input Offset Voltage	Vos	R _S = 50Ω	2	1	3	2	6	mV MAX
Input Bias Current	I _B		±18		±18	_	_	nA MAX
Input Offset Current	los		14	_	14		_	nA MAX
Large-Signal Voltage Gain	A _{VO}	$V_O = \pm 10V$, $R_L = 2k\Omega$	30	150	30	75	50	V/mV MIN
Input Voltage Range	IVR		±10.2	±10.2	±10.2	±10.2	±10.1	V MIN
Common-Mode Rejection Ratio	CMRR	V _{CM} = ±IVR	82	86	82	86	82	dB MIN
Power Supply Rejection Ratio	PSRR	$V_S = \pm 10 \text{ to } \pm 16V$ $V_S = \pm 10 \text{ to } \pm 15V$	100	51	100	80	100	μV/V MAX
Output Voltage Swing	v _o	$R_L = 10k\Omega$ $R_L = 2k\Omega$	± 12	±12 ±11	±12 —	±12 ±11	±12 ±11	V MIN
Supply Current	I _{SY}			8.5	_	8.5	12.0	mA MAX

NOTES:

For 25°C characteristics of NT & GT devices, see N & G characteristics respectively.

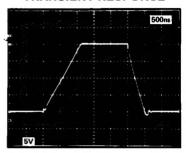
Electrical tests are performed at wafer probe to the limits shown. Due to variations in assembly methods and normal yield loss, yield after packaging is not guaranteed for standard product dice. Consult factory to negotiate specifications based on dice lot qualification through sample lot assembly and testing.

TYPICAL ELECTRICAL CHARACTERISTICS at $V_S = \pm 15V$, $T_A = +25^{\circ}$ C, unless otherwise noted.

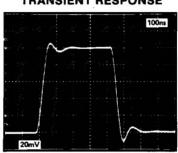
PARAMETER	SYMBOL	CONDITIONS	OP-215NT TYPICAL	OP-215N TYPICAL	OP-215GT TYPICAL	OP-215G TYPICAL	OP-215GR TYPICAL	UNITS
Average Input Offset Voltage Drift	TCVos	Unnulled R _p = 100kΩ	2	2	3	3	4	μV/° C
Average Input Offset Voltage Drift	TCV _{OSn}	Nulled R _P = 100kΩ	0.5	0.5	1	1	2	μV/° C
Input Offset Current	los		3	3	3	3	3	pA
Input Bias Current	I _B		±15	±15	±15	±15	±15	pΑ
Slew Rate	SR	A _{VCL} = +1	17	17	16	16	15	V/μs
Settling Time	t _S	to 0.01% to 0.05% to 0.10%	2.2 1.1 0.9	2.2 1.1 0.9	2.3 1.1 0.9	2.3 1.1 0.9	2.4 1.2 1.0	μS
Gain Bandwidth Product	GBW		6.0	6.0	5.7	5.7	5.4	MHz
Closed-Loop Bandwidth	CLBW	A _{VCL} = +1	14	14	13	13	12	MHz
Input Noise Voltage Density	en	f _O = 100Hz f _O = 1000Hz	20 15	20 15	20 15	20 15	20 15	nV/√Hz
Input Noise Current Density	in	f _O = 100Hz f _O = 1000Hz	0.01	0.01	0.01	0.01	0.01	pA/√ Hz
Input Capacitance	C _{IN}		3	3	3	3	3	pF

TYPICAL PERFORMANCE CHARACTERISTICS

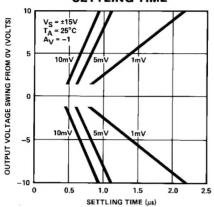
LARGE-SIGNAL TRANSIENT RESPONSE



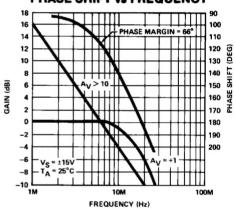
SMALL-SIGNAL TRANSIENT RESPONSE



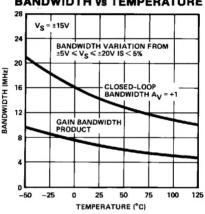
SETTLING TIME



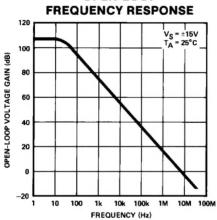
CLOSED-LOOP BANDWIDTH AND PHASE SHIFT VS FREQUENCY



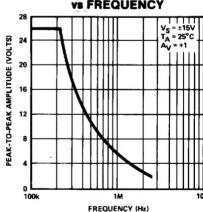
BANDWIDTH vs TEMPERATURE

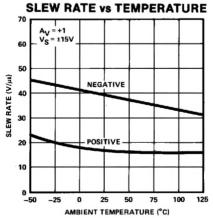


OPEN-LOOP

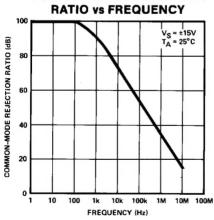


MAXIMUM OUTPUT SWING vs FREQUENCY



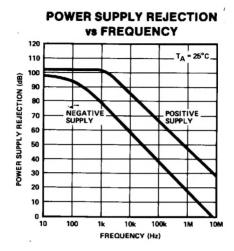


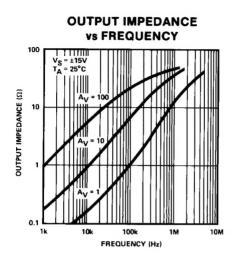
COMMON-MODE REJECTION

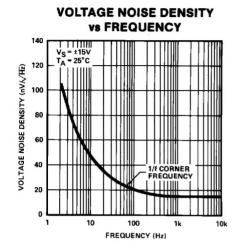


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TYPICAL PERFORMANCE CHARACTERISTICS

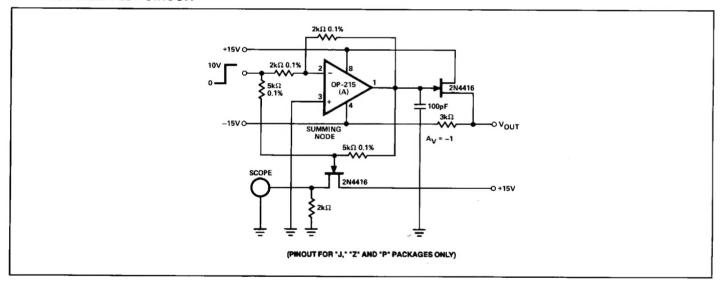




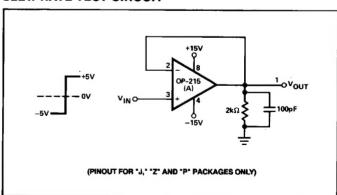


BASIC CONNECTIONS

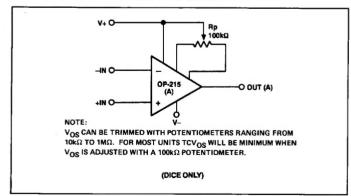
SETTLING TIME TEST CIRCUIT



SLEW RATE TEST CIRCUIT

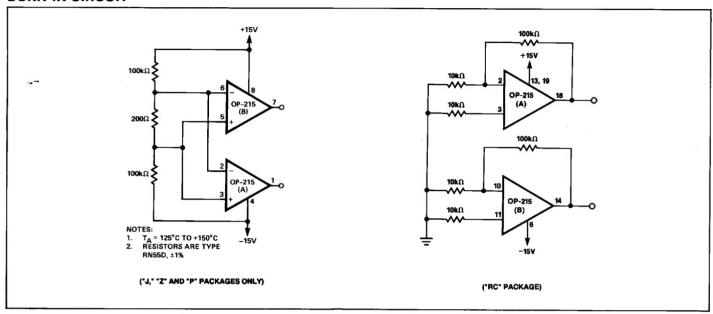


INPUT OFFSET VOLTAGE NULLING



BASIC CONNECTIONS

BURN-IN CIRCUIT



APPLICATIONS INFORMATION

DYNAMIC OPERATING CONSIDERATIONS

As with most amplifiers, care should be taken with lead dress, component placement and supply decoupling in order to ensure stability. For example, resistors from the output to an input should be placed with the body close to the input to minimize "pick-up" and maximize the frequency of the feedback pole by minimizing the capacitance from the input to ground.

A feedback pole is created when the feedback around any amplifier is resistive. The parallel resistance and capacitance from the input of the device (usually the inverting input) to

AC ground sets the frequency of the pole. In many instances, the frequency of this pole is much greater than the expected 3dB frequency of the closed-loop gain and consequently there is negligible effect on stability margin. However, if the feedback pole is less than approximately six times the expected 3dB frequency, a lead capacitor should be placed from the output to the negative input of the op amp. The value of the added capacitor should be such that the RC time constant of this capacitor and the resistance it parallels is greater than, or equal to, the original feedback-pole time constant.

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